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Customer No.: 31561
Application No.: 10/711,540
Docket No.: 13365-US-PA

REMARKS

Present Status of the Application

The Office Action rejected claims 25 and 28-29 under 35 U.S.C. 102(b) as being anticipated by Huang (U.S. Publication No. 2003/0103339). The Office Action also rejected claims 30-34 under 35 U.S.C. 103(a) as being unpatentable over Huang (U.S. Publication No. 2003/0103339).

Discussion of Office Action Rejections

1. The Office Action rejected claims 25 and 28-29 under 35 U.S.C. 102(b) as being anticipated by Huang (U.S. Publication No. 2003/0103339). In response thereto, Applicants respectfully traverse the rejections for at least the reasons set forth below.

Independent claim 25 recites the features as follows:

25. A chip with polymer thereon, comprising at least:
a chip having an active surface;
a polymer, disposed at periphery of the active surface of the chip extending to sidewalls of the chip; and
a plurality of wires electrically connecting the chip and a carrier for carrying the chip, wherein an end of each of the wires connected with the active surface of the chip is covered by the polymer and the other end of each of the wires is exposed outside of the polymer.

(emphasis added)

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Claims 28-29 recite similar features as set forth in claim 25.

In re U.S. Publication No. 2003/0103339, Huang fails to disclose that "an end of each of the wires connected with the active surface of the chip is covered by the polymer and the other end of each of the wires is exposed outside of the polymer". Therefore, the 102(b) rejection of claims 25 and 28-29 should be withdrawn. When the end of each wire connected with the active surface of the chip is covered by the polymer, the low-K peeling problem described in paragraphs [0007]-[0008] of the present application can be effectively reduced. Therefore, the claimed invention is non-obvious for one ordinary skilled in the art, since Huang fails to teach or suggest the liquid compound (402) shown in figure 7 can solve the low-K peeling problem occur at the periphery of the active surface of the chip.

2. The Office Action also rejected claims 30-34 under 35 U.S.C. 103(a) as being unpatentable over Huang (U.S. Publication No. 2003/0103339). In response thereto, Applicants respectfully traverse the rejections for at least the reasons set forth below.

In re U.S. Patent No. 6,117,705, Huang fails to disclose that "an end of each of the wires connected with the active surface of the chip is covered by the polymer and the other end of each of the wires is exposed outside of the polymer". Specifically, in re figure 7 of U.S. Publication No. 2003/0103339, Huang disclosed that "an end of each wire 240 connected with the lead 204 of leadframe is covered by the liquid compound 402". Therefore, Applicants assert that Huang fails to disclose, teach, or suggest that

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"an end of each of the wires connected with the active surface of the chip is covered by the polymer and the other end of each of the wires is exposed outside of the polymer" and claims 30-34 should be novel and non-obvious.

For at least the foregoing reasons, Applicant respectfully submits that all presently pending claims 25 and 28-34 patently define over the prior art references, and should be allowed.

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CONCLUSION

For at least the foregoing reasons, it is believed that the pending claims 25 and 28-34 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

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Respectfully submitted,

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